

Small Signal Product

Surface Mount Schottky

FEATURES

- Designed for mounting on small surface
- Extremely thin / leadless package
- Low capacitance
- Low forward voltage drop
- Packing code with suffix "G" means green compound (halogen-free)



1005



MECHANICAL DATA

- Case: 1005
- Terminal: Gold plated, solderable per MIL-STD-750, method 2026
- Polarity: Indicated by cathode band
- Weight: 6 mg (approximately)
- Marking code: BF

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)			
PARAMETER	SYMBOL	VALUE	UNIT
Repetitive Peak Reverse Voltage	V _{RRM}	30	V
Reverse Voltage	V _R	30	V
RMS Reverse Voltage	V _{R(RMS)}	21	V
Average Forward Current	I _O	200	mA
Repetitive Peak Forward Current	I _{FRM}	0.3	A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rate Load	I _{FSM}	600	mA
Power Dissipation	P _d	200	mW
Forward Voltage I _F = 0.1 mA I _F = 1 mA I _F = 10 mA I _F = 30 mA I _F = 100 mA	V _F	0.24	V
		0.32	
		0.40	
		0.50	
		1.00	
Reverse Leakage Current V _R = 25 V	I _R	2	μA
Typical Capacitance Between Terminals V _R = 1 V , f = 1.0 MHz Reverse Voltage	C _J	10	pF
Reverse Recovery Time (I _F = I _R = 10mA, I _{RR} = 0.1×I _R , R _L =100Ω)	t _{rr}	5	ns
Junction Temperature	T _J	-65 to +125	°C
Storage Temperature	T _{STG}	-65 to +125	°C

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RATINGS AND CHARACTERISTICS CURVES

($T_A=25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Characteristics

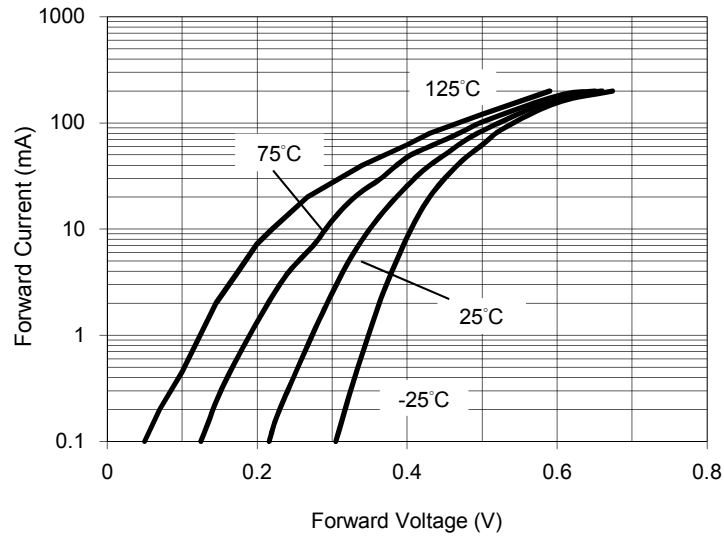


Fig. 2 Reverse Characteristics

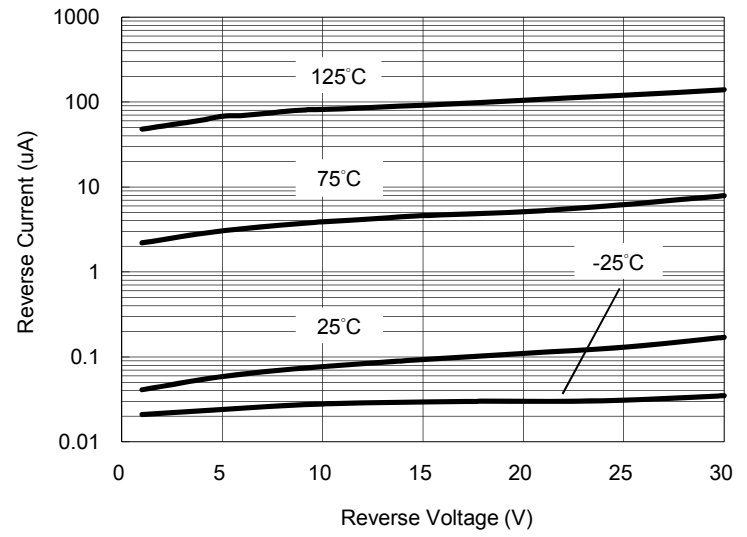


Fig. 3 Capacitance Between Terminals Characteristics

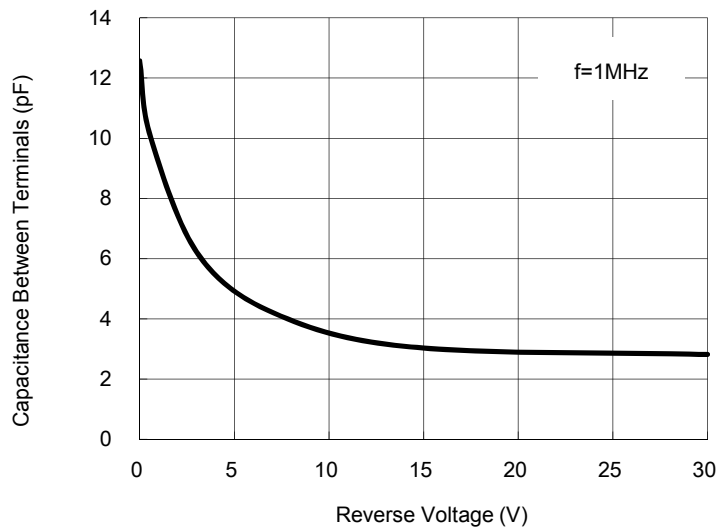
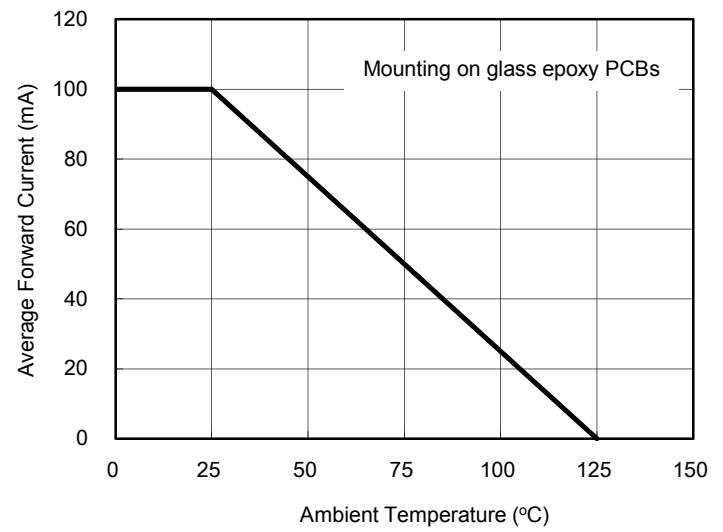


Fig. 4 Current Derating Curve



Small Signal Product

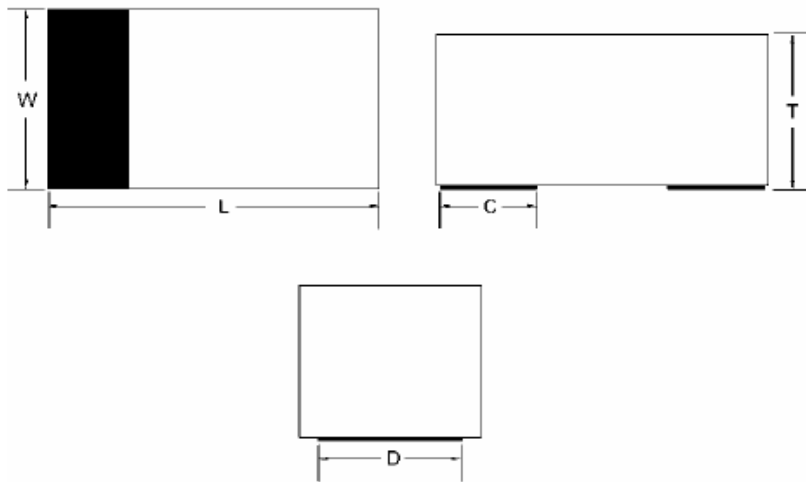
ORDERING INFORMATION					
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
TSS54L	-xx (Note 1)	RW	G	1005	4K / 7" Reel

Note 1: Part No. Suffix „-xx “ would be used for special requirement

EXAMPLE					
PREFERRED PART NO.	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
TSS54L RWG	TSS54L		RW	G	Multiple manufacture source Green compound
TSS54L-F0 RWG	TSS54L	-F0	RW	G	Define manufacture source Green compound

PACKAGE OUTLINE DIMENSION

1005



DIM.	Unit (mm)			Unit (inch)		
	Min	Typ	Max	Min	Typ	Max
L	2.40	-	2.60	0.094	-	0.102
W	1.10	-	1.30	0.043	-	0.051
T	0.70	-	0.90	0.028	-	0.035
C	-	0.50	-	-	0.020	-
D	-	1.00	-	-	0.039	-

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